

Supplier Name: Texas Instruments Inc. (DUNS# 00-732-1904)
 Contact Info: ti.com/support
 Form/Declaration Type: Distribute - RoHS and IEC 62474 DB
 Created on: 06/09/2022

Details for "TLV9064IPWT"

Current Product Information

TI part number	Lead finish/Ball material	MSL rating/peak reflow	Assembly site	Package Pins	Package body size (mm)	Total device mass (mg)*
TLV9064IPWT	SN	Level-2-260C-1 YEAR	Ext-Mfg	PW 14	5x4.4x1.0	61.8

*Total Device Mass

The summary mass is a rounded value and will be within approximately +/- 10% of the detailed mass value.

Environmental Ratings Information

RoHS	REACH	Green	IEC 62474 DB
Yes	Yes	Yes	Yes

Component Information

Component	Substance	CAS Number	Amount (mg)	Homogeneous Material Level		Component Level	
				Percentage %	ppm	Percentage %	ppm
Bond Wire							
Copper and Its Alloys	Copper	7440-50-8	0.046869	96.67698	966770	0.075872	759
Precious Metals	Gold	7440-57-5	0.000259	0.534241	5342	0.000419	4
Precious Metals	Palladium	7440-05-3	0.001352	2.788779	27888	0.002189	22
Sub-Total			0.04848	100	1000000	0.07848	785
Die Attach Adhesive							
Precious Metals	Silver	7440-22-4	0.090241	82	820000	0.146083	1461
Thermoplastics	Epoxy	85954-11-6	0.019809	18	180000	0.032067	321
Sub-Total			0.11005	100	1000000	0.17815	1781
Lead Frame							
Copper and Its Alloys	Copper	7440-50-8	21.1232	94.2105	942105	34.194351	341944
Copper and Its Alloys	Iron	7439-89-6	0.0112	0.049953	500	0.018131	181
Copper and Its Alloys	Phosphorus	7723-14-0	0.0056	0.024976	250	0.009065	91
Magnesium and Its Alloys	Magnesium	7439-95-4	0.0112	0.049953	500	0.018131	181
Nickel and Its Alloys	Nickel	7440-02-0	0.5376	2.397722	23977	0.87027	8703
Other Inorganic Materials	Silicon	7440-21-3	0.1568	0.699336	6993	0.253829	2538
Other Nonferrous Metals and Alloys	Lead	7439-92-1	0.00224	0.009991	100	0.003626	36
Other Nonferrous Metals and Alloys	Manganese	7439-96-5	0.00224	0.009991	100	0.003626	36
Precious Metals	Silver	7440-22-4	0.5712	2.54758	25476	0.924662	9247
Sub-Total			22.42128	100	1000000	36.29569	362957
Lead Frame Plating							
Other Nonferrous Metals and Alloys	Tin	7440-31-5	0.6	100	1000000	0.971283	9713
Sub-Total			0.6	100	1000000	0.971283	9713
Mold Compound							
Other Inorganic Materials	Fused Silica	60676-86-0	32.405562	84.850001	848500	52.458299	524583
Other Plastics and Rubber	Carbon Black	1333-86-4	0.057287	0.149999	1500	0.092737	927
Thermoplastics	Epoxy	85954-11-6	5.728738	15	150000	9.273712	92737
Sub-Total			38.191587	100	1000000	61.824748	618247
Semiconductor Device							
Ceramics / Glass	Doped Silicon	7440-21-3	0.40255	100	1000000	0.65165	6517
Sub-Total			0.40255	100	1000000	0.65165	6517
Total			61.773947			100	1000000

Important Note

The ppm calculations are at the **homogeneous material** level and are maximum concentration values. The ppm displayed represents the **homogeneous material** with the highest ppm for that substance. The amount (mg) calculations represent the maximum total amount of each substance within the component.

The ppm calculations are at the **component** level and are average concentration values. The amount (mg) calculations represent the average total amount of each substance within the **component**.

[See Glossary of Terms for more details.](#)

Important Part Information

There is a remote possibility the Customer Part Number (CPN) your company uses could reference more than one TI part number. This is due to two or more users (EMSI's or subcontractors) using the same CPN for different TI part numbers. If this occurs, please check your Customer Part Number and cross reference it with the TI part number seen on this page.

Product Content Methodology

[For an explanation of the methods used to determine material weights, See Product Content Methodology](#)

Material Declaration Certificate for Semiconductor IC Packaged Products

TI certifies that the material content information provided by TI is representative and accurate to the best of their knowledge based on material information provided by its suppliers and their combination into finished IC packaged products. TI semiconductor products designated to be "Pb-free", "Green" or "RoHS Exempt" fully meets the latest EU RoHS Directive requirements along with other legislation as seen in the former JIG-101 list that has been transferred to the IEC 62474 database.

Important Information/Disclaimer

TI bases its material content information on information provided by third-party suppliers and has taken, and continues to take, reasonably diligent steps to provide any required or available information. TI may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers may consider certain information to be proprietary, and thus certain information may not be available for release by TI. The material content information is provided by TI "as is."

[For additional information, please contact TI customer support.](#)

[Signature: \(click here for a fuller statement with a signed certificate\)](#)

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 For further environmental statements, please go to www.ti.com/eoinfo
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RoHS: Means TI semiconductor products that are compliant with the current RoHS requirement that the maximum concentration values of the ten substances listed in RoHS Annex II do not exceed 0.1 % by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI semiconductor products labeled as "RoHS Compliant" are suitable for use in specified lead-free processes. TI may also reference these types of semiconductor products as "Pb-Free." These TI semiconductor products are also fully compliant with GADSL and the IEC 62474 database for electronic requirements.

RoHS Exempt: Means TI semiconductor products that contain lead (Pb) above the RoHS Annex II threshold, but that fall within one of the specific RoHS exemptions noted above or documented in <http://www.ti.com/lit/pdf/szzq088>

Green: Means the content of Chlorine (Cl) and Bromine (Br)-based flame retardants meet JS709B low halogen requirements of <=1 000ppm threshold; Antimony trioxide (Sb203) contained in halogen based flame retardant materials meets the <=1 000ppm threshold requirement; and Beryllium Oxide (BeO) is <=1000ppm.